

METHOD FOR DETERMINING POLISHING PAD HEIGHT AND POLISHING SYSTEM

ABSTRACT

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Provided is a method for determining an accurate height of a polishing pad even when a dressing load applied to the polishing pad is changed. A method for determining a polishing pad height is provided. The method includes measuring a reference dresser height that is a height of a dressing surface (50a) of a dresser (50) when a polishing surface (22a) of a polishing pad (22) in an unused state is being pressed with a reference dressing load for polishing a substrate, calculating a correction amount for a dresser height corresponding to an amount of change in dressing load from the reference dressing load, measuring a current dresser height that is a current height of the dressing surface (50a) of the dresser (50) when the polishing surface (22a) of the polishing pad (22) is being pressed, and correcting the current dresser height using the correction amount.

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FIG. 2